MUR6060PT

60.0 AMP HIGH EFFICIENCY RECTIFIERS



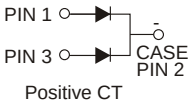
VOLTAGE RANGE
600 Volts
CURRENT
30.0 *2 Ampere

FEATURES

* Low forward voltage drop
* High current capability
* High reliability
* High surge current capability
* Good for switching mode application

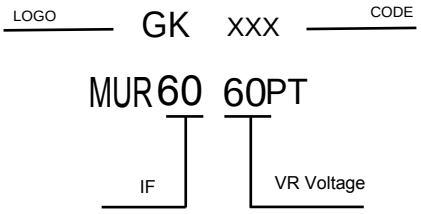
MECHANICAL DATA

* Case: Molded plastic
* Epoxy: UL 94V-0 rate flame retardant
* Lead: Axial leads, solderable per MIL-STD-202, method 208 guranteed
* Polarity: Color band denotes cathode end
* Mounting position: Any



Positive CT





MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25˚C ambient temperature uniess otherwies specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

TYPE NUMBER	MU6060PT	UNITS
Maximum Recurrent Peak Reverse Voltage	600	V
Maximum RMS Voltage	420	V
Maximum DC Blocking Voltage	600	V
Maximum Average Forward Rectified Current	60.0	A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	500	A
Maximum Instantaneous Forward Voltage at 30.0A Type at 30.0A Type at 20.0A Type at 10.0 A	1.65 1.35 1.28 1.18	V
Maximum DC Reverse Current Ta=25˚C	5	μA
at Rated DC Blocking Voltage Ta=100˚C	100	μA
Maximum Reverse Recovery Time (Note 1)	45	nS
Typical Junction Capacitance (Note 2)	200	pF
Typical Thermal Resistance $R_{\theta J-C}$ (Note 3)	1.8	˚C/W
Typical Thermal Resistance $R_{\theta J-A}$ (Note 4)	50	˚C/W
Operating and Storage Temperature Range T_J, T_{STG}	-65 — +175	˚C

NOTES:

1. Reverse Recovery Time test condition: IF=0.5A, IR=1.0A, IRR=0.25A
2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
3. Between junction and case
4. Between junction and Air

RATING AND CHARACTERISTIC CURVES

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

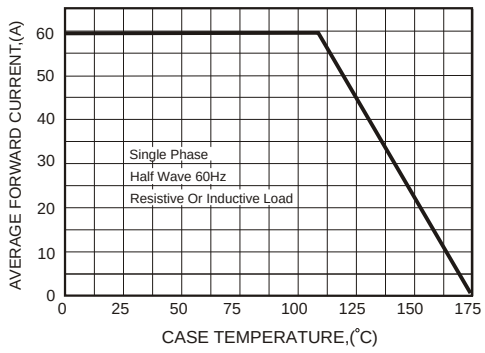


FIG.2-TYPICAL FORWARD CHARACTERISTICS

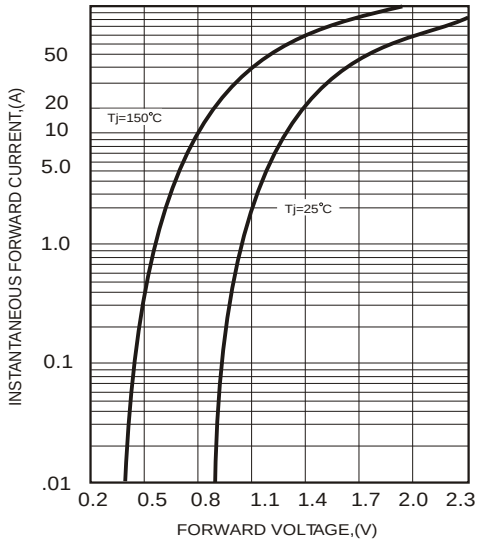


FIG.3 - TYPICAL REVERSE CHARACTERISTICS

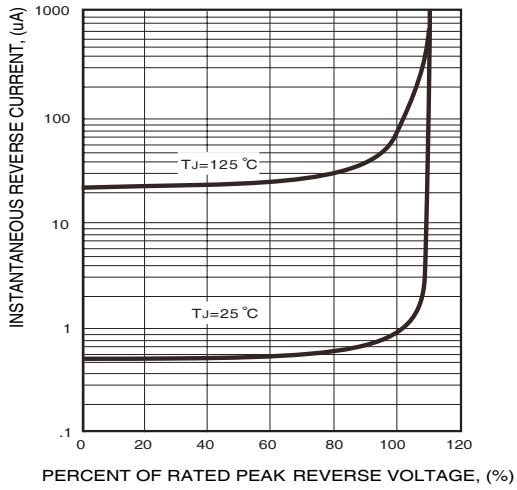


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

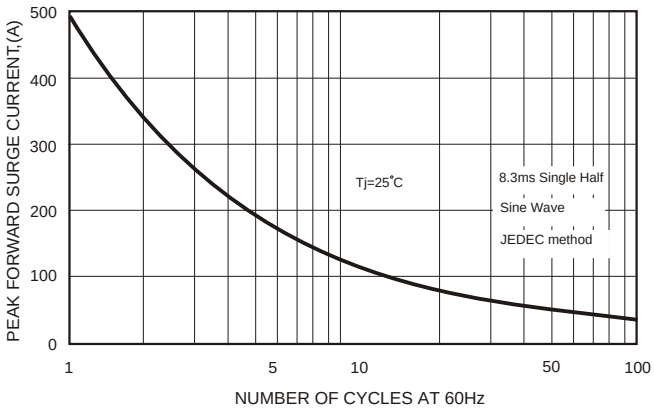
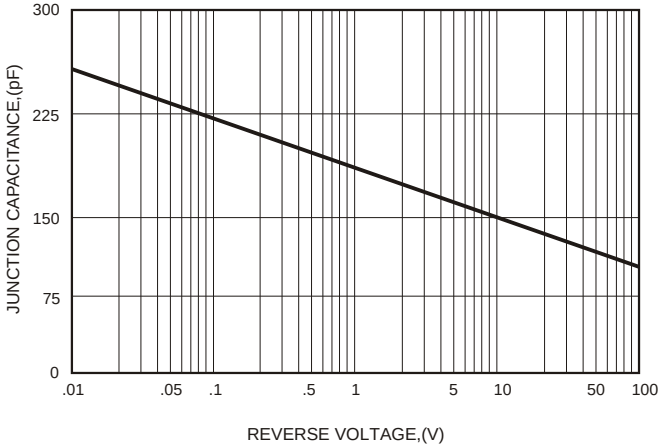


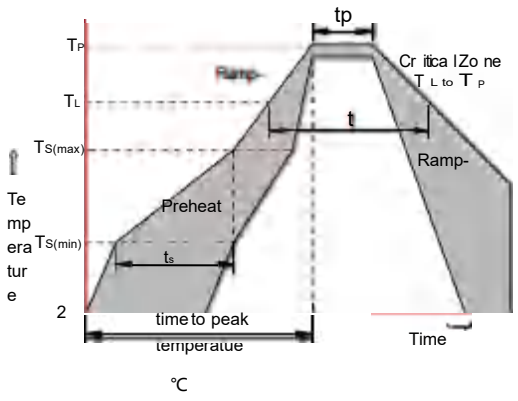
FIG.5-TYPICAL JUNCTION CAPACITANCE



Soldering parameters

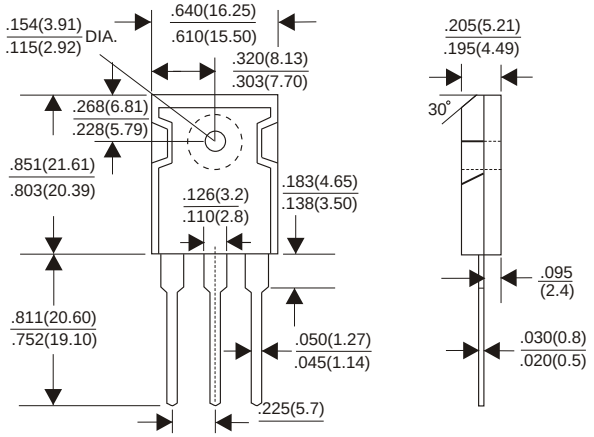
Reflow Condition		Pb-Free assembly (see as bellow)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150℃
	-Temperature Max($T_{s(max)}$)	+200℃
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3℃/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3℃/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217℃
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)℃
Time within 5℃ of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6℃/sec. Max
Time 25℃ to Peak Temp (T_P)		8 min. Max
Do not exceed		+260℃

FIG5: Reflow condition



Package Dimensions & Suggested Pad Layout

TO-247



Dimensions in inches and (millimeters)